


**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	EMBEDDED PROCESSING/25/15422	
<b>1.3 Title of PCN</b>	ASE KaoHsiung (Taiwan) additional source for STM32F74/75xx, STM32F76/77xx listed products in TFBGA 13X13 216L package and STM32F20/21xx, STM32F40/41xx, STM32F42/43xx listed products in UFBGA 10X10 176+25 package.	
<b>1.4 Product Category</b>	STM32F74/75xx, STM32F76/77xx, STM32F20/21xx, STM32F40/41xx and STM32F42/43xx	
<b>1.5 Issue date</b>	2025-09-16	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	SCHAEFER MARC
<b>2.1.2 Phone</b>	+49 89460062136
<b>2.1.3 Email</b>	marc.schaefer@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Patrick AIDOUNE
<b>2.1.2 Marketing Manager</b>	Veronique BARLATIER
<b>2.1.3 Quality Manager</b>	Pascal NARCHE

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	ASE KaoHsiung (Taiwan)

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	<p>Current assembly sites (depending on package/product):</p> <ul style="list-style-type: none"> <li>- AMKOR ATP (Philippine) Gold for Crolles, TSMC &amp; Rousset Dice,</li> <li>- AMKOR ATP (Philippine) Copper Palladium wire for Crolles, TSMC Dice,</li> <li>- ASE Kaohsiung (Taiwan) Gold wire for Crolles, TSMC &amp; Rousset Dice,</li> <li>- ASE Kaohsiung (Taiwan) Copper Palladium wire for Crolles &amp; TSMC Dice,</li> </ul> <p>You may refer to 15422_Additional information.pdf document for further details.</p>	<p>Current assembly sites: (depending on package/product):</p> <ul style="list-style-type: none"> <li>- AMKOR ATP (Philippine) Gold for Crolles, TSMC &amp; Rousset Dice,</li> <li>- AMKOR ATP (Philippine) Copper Palladium wire for Crolles, TSMC Dice,</li> <li>- ASE Kaohsiung (Taiwan) Gold wire for Crolles, TSMC &amp; Rousset Dice,</li> <li>- ASE Kaohsiung (Taiwan) Copper Palladium wire for Crolles &amp; TSMC Dice,</li> </ul> <p>Additional assembly site for extended capacity:</p> <ul style="list-style-type: none"> <li>- ASE Kaohsiung (Taiwan) Copper Palladium wire for Rousset Dice.</li> </ul>
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	No Impact on Form, Fit or Function	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	Due to the success on the market of STM32 devices, ST General Purpose and Automotive Microcontrollers division decided to qualify an additional back-end site to maintain state of the art service level to our customers thanks to extra capacity.
<b>5.2 Customer Benefit</b>	SERVICE IMPROVEMENT

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	Change is visible in the marking. Please refer to PCN 15422_Additional information.pdf document for further details.
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2025-10-07
<b>7.2 Intended start of delivery</b>	2025-11-07

7.3 Qualification sample available?	Upon Request
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8. Qualification / Validation			
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8.1 Description	15422 MDRF-GPAM-RER2520 PCN15422- ASEKH TFBGA216L and UFBGA176+25- Reliability Plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2025-09-16

9. Attachments (additional documentations)			
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15422 Public product.pdf 15422 MDRF-GPAM-RER2520 PCN15422- ASEKH TFBGA216L and UFBGA176+25- Reliability Plan.pdf 15422 _Additional information.pdf			
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10. Affected parts		
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10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F427IIH6TR	
	STM32F429IIH6TR	

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